NEW PRODUCT

RS1MDF

1.0A SURFACE MOUNT FAST RECOVERY RECTIFIER

Product Summary (@T_A = +25°C)

V_{RRM} (V)	I_O (A)	V_F Max (V)	I_R Max (μA)
1,000	1	1.3	5

Features and Benefits

- Glass Passivated Die Construction
- Fast Recovery Time for High Efficiency
- Surge Overload Rating to 30A Peak
- High Current Capability
- Low Profile Design, Package Height Less than 1.1mm
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **An Automotive-Compliant Part is Available Under Separate Datasheet (RS1MDFQ)**

Description and Applications

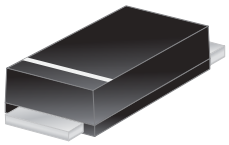
The RS1MDF is a rectifier packaged in the low profile D-FLAT package. Providing fast recovery time for high efficiency, this device is ideal for use in general rectification applications such as:

- Switching Mode Power Supplies
- Chargers
- LED Lighting
- Inverters
- AC-DC Adapters

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e3
- Polarity: Cathode Band
- Weight: 0.035 grams (Approximate)

D-FLAT



Top View

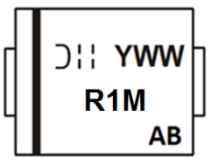
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RS1MDF-13	AEC-Q101	D-FLAT	10,000/Tape & Reel

Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

D-FLAT



R1M= Product Type Marking Code
= Manufacturers' Code Marking
YWW = Date Code Marking
Y = Last Digit of Year (ex: 6 for 2016)
WW = Week Code (01 to 53)
AB = Foundry and Assembly Code

NEW PRODUCT

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)	V_{RRM} V_{RWM} V_R	1,000	V
RMS Reverse Voltage	$V_{R(RMS)}$	700	V
Average Rectified Output Current @ T_A = +100°C	I_O	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	30	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 7)	$R_{\theta JT}$	31	°C/W
Typical Thermal Resistance, Junction to Air (Note 7)	$R_{\theta JA}$	83	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	1,000	—	—	V	I_R = 10μA
Forward Voltage Drop	V_F	—	0.95 0.83	1.3 —	V	I_F = 1A, T_J = +25°C I_F = 1A, T_J = +125°C
Leakage Current (Note 5)	I_R	—	0.2 5	5 —	μA	V_R = 1,000V, T_J = +25°C V_R = 1,000V, T_J = +125°C
Reverse Recovery Time	t_{rr}	—	140	500	ns	I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A
Total Capacitance	C_T	—	5	—	pF	V_R = 4.0V_{DC}, f = 1MHz

Notes:
5. Short duration pulse test used to minimize self-heating effect.
6. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.1" x 0.15" copper pads.
7. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pads.

NEW PRODUCT

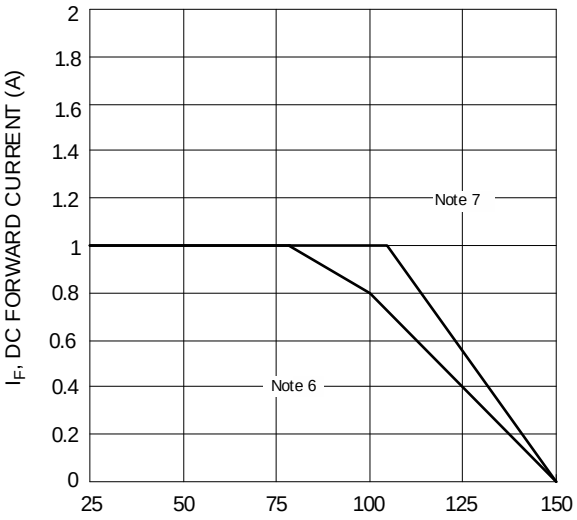


Figure 1 DC Forward Current Derating

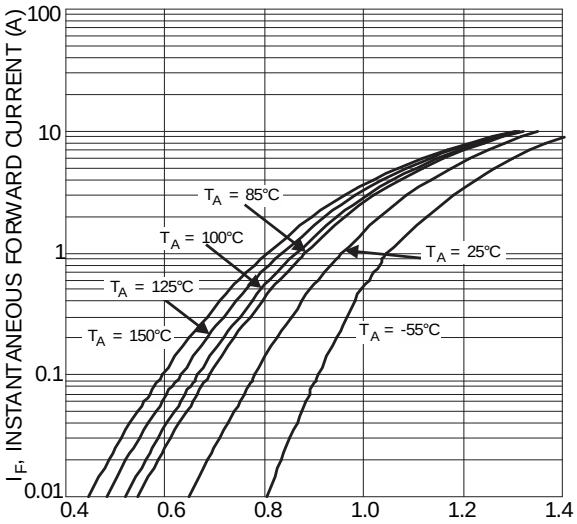


Figure 2 Typical InstantanousForward Voltage

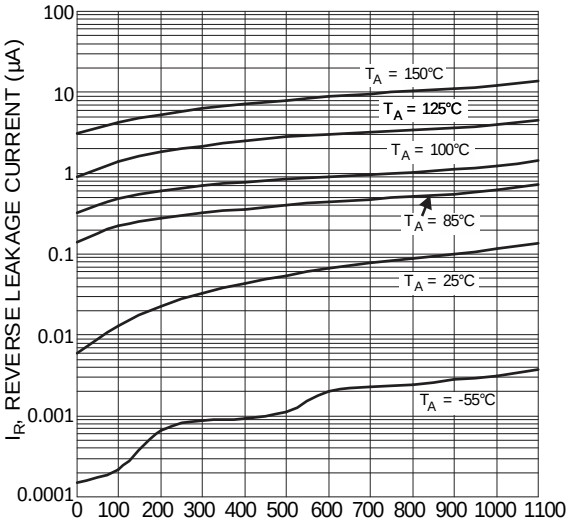


Figure 3 Typical Instantaneous Reverse Characteristics

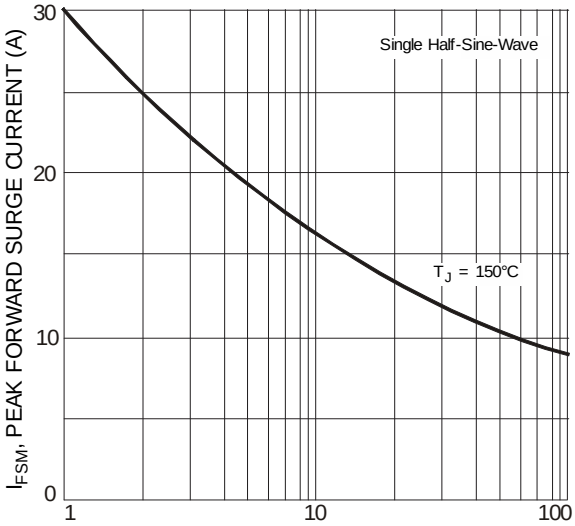


Fig. 4 Forward Surge Current Derating Curve

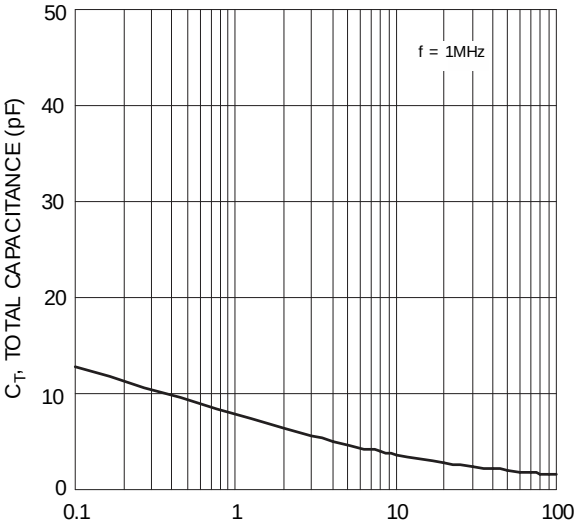


Figure 5 Total Capacitance vs. Reverse Voltage

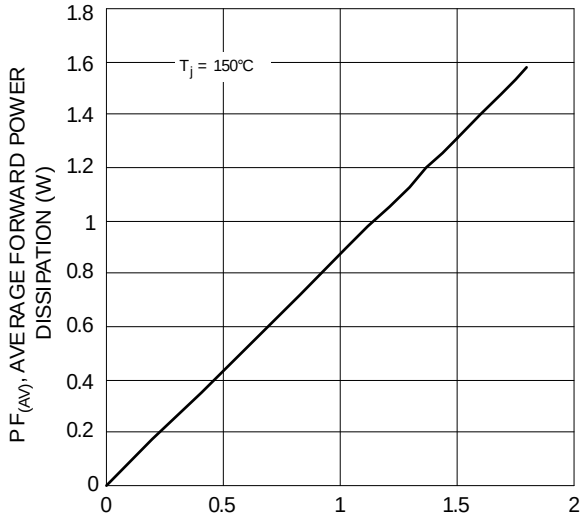


Figure 6 Forward Power Dissipation

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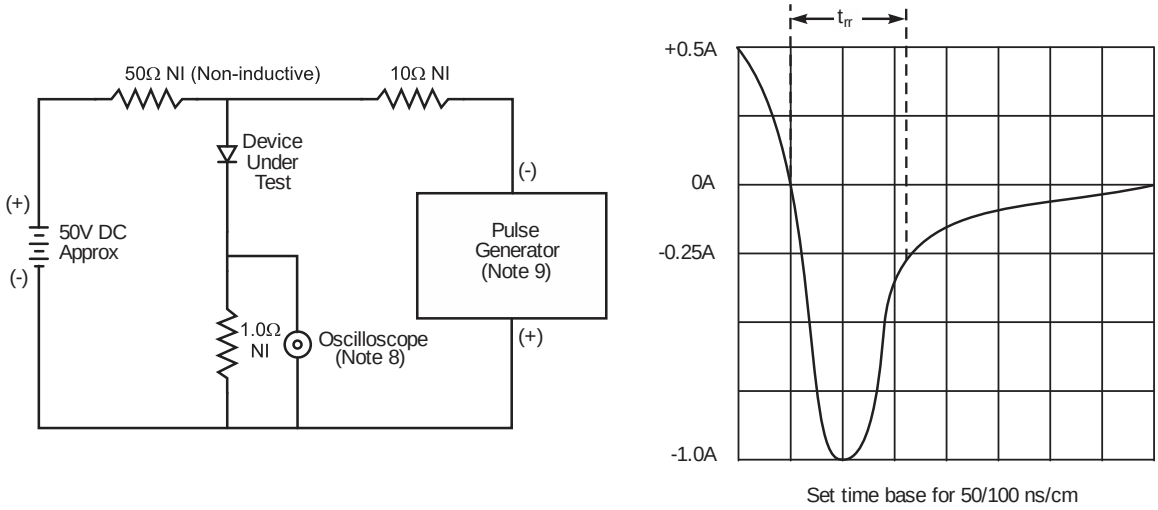
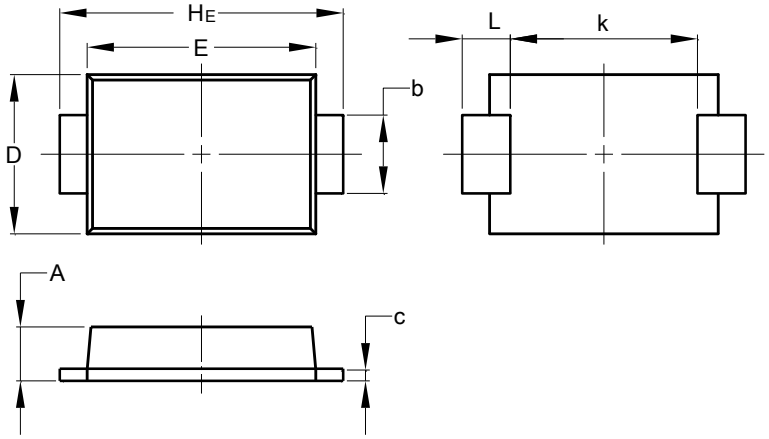


Figure 7 Reverse Recovery Time Characteristic and Test Circuit

Notes: 8. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
9. Rise Time = 10ns max. Input Impedance = 50Ω.

Package Outline Dimensions

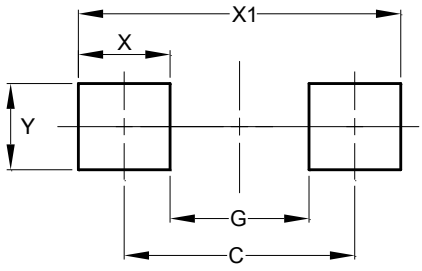
Please see http://www.diodes.com/package-outlines.html for the latest version.



D-FLAT		
Dim	**Min**	**Max**
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
k	2.80	-
H_E	5.00	5.60
L	0.50	1.30
All Dimensions in mm		

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
C	4.65
G	2.80
X	1.85
X1	6.50
Y	1.70

NEW PRODUCT

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Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9